



IN THE UNITED STATES
PATENT AND TRADEMARK OFFICE

PATENT APPLICATION

INVENTORS:

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CASE: 60-40-1-1

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TITLE: STACKED MODULE PACKAGE

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EXAMINER DiLinh P. Nguyen

THE COMMISSIONER OF PATENTS AND TRADEMARKS
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SIR:

In response to the Office action mailed 08/28/2002 please enter the following
amendments and consider the remarks that follow.

In the claims:

Please amend claim 1 to read:

1. A stacked MCM package comprising a substrate, a digital MCM on the
substrate, an RF MCM on the digital MCM, and means electrically
connecting the RF MCM to the substrate, and wherein the RF MCM and
the digital MCM are electrically isolated.